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#### Analysis of micro-dispersed PCM-composite boards behavior in a 1 building's wall for different seasons 2 Kamal EL OMARI<sup>a,\*</sup>, Yves LE GUER<sup>a</sup>, Pascal BRUEL<sup>b</sup> 3 <sup>a</sup>Université de Pau et des Pays de l'Adour (UPPA), 4 Laboratoire des Sciences de l'Ingénieur Appliquées à la Mécanique et au génie électrique (SIAME), 5 64000 Pau, France. 6 <sup>b</sup> CNRS - Laboratoire de Mathématiques et de leurs Applications, 7 Inria Cagire Team, 64000 Pau, France. 8

## 9 Abstract

The integration of phase change materials (PCMs) in buildings especially in their walls 10 is the subject of more than a decade of growing interest due to their potentialities for 11 energy saving and enhancement of thermal comfort. The present investigation concerns 12 the applications related to thermal insulation. The idealized composite wall considered 13 here numerically can be thought of as resulting from the incorporation of shape-stabilized 14 PCM particles in a polymer matrix. A novel model is developed to study the thermal 15 behavior of this PCM-composite when used as a planar insulating material submitted 16 to variable thermal modulations on one of its faces. The numerical model couples the 17 heat transfer in the wall with the heat transfer and the crystallization/melting process 18 within PCM inclusions considered as spherical. Both processes are modeled by a finite 19 volume approach combined with the enthalpy method to account for the phase change. 20 Simulation results are used to monitor the temperatures in the wall and quantify the en-21 ergy exchanges between its two sides. The thickness of the wall and the volume fraction 22 of the incorporated PCM were varied in this study. This analysis permits to point out 23 the configurations for which the negative effect of the higher thermal conductivity of the 24 PCM outweighs the benefits related to its latent heat. The analysis is extended to dif-25 ferent external temperature modulations representing different typical seasons/climates. 26 The results show the impact of the choice of the PCM phase change temperature on 27 the wall thermal efficiency over the year. For the case investigated, it was shown that a 28 PCM composite board with increased performances during a summer day exhibits a de-29 graded behavior during a winter day when compared to a pure (without PCM) insulation 30 material. 31

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Keywords: Phase change material (PCM), composite board, dispersed PCM, building
 thermal insulation, enthalpy method.

## 34 1. Introduction

It is widely accepted that buildings and particularly those dedicated to housing repre-35 sent a significant potential for energy saving, mainly related to the use of heating and air 36 conditioning systems [1, 2, 3]. In that domain, the objective of the research and devel-37 opment community is to develop innovative approaches to save energy while preserving 38 if not enhancing the thermal comfort of the buildings' inhabitants. In that framework, 39 quite a significant number of recent studies focused on the use of phase change materials 40 (PCMs) in buildings. They can be used as standalone systems to store energy, embedded 41 in the structure [4, 5, 6] or in the external envelope [7, 8, 9]. The integration of PCMs re-42 sults in an increase of the building thermal inertia, especially for lightweight construction. 43 Combined with an efficient insulating material, it helps to reduce the indoor temperature 44 peaks related to the outdoor temperature evolution and the solar radiation received at the 45 external facades. Different techniques allow the integration of PCMs in building envelope 46 materials: impregnation, incorporation of micro-encapsulations or macro-encapsulation in 47 the form of slabs for example [10, 11, 12]. These solutions have attracted a great interest 48 and have been the subject of a significant number of both numerical and experimental 49 studies [13, 14, 15, 16, 17, 18]. There exist also encapsulation free techniques based on the 50 direct incorporation of the PCM during the fabrication process or on immersion methods 51 for natural porous materials [19]. For PCM-composite boards based on natural polymer 52 matrices, one promising method involves the use of the low-energy emulsification tech-53 nique [20, 21]. Since the plain insulation panels e.g. PCM-free commercially available 54 have standardized thicknesses, the development of a PCM-composite board offering the 55 same thickness range seems a reasonable choice. But even the choice of the proper PCM 56 to be incorporated in a given matrix is not straightforward though. First, because of its 57 relatively high conductivity when compared to that of the matrix, the overall thermal 58 behavior of the PCM-composite board may be degraded under certain conditions when 59 compared to that of its PCM free counterpart. Second, a melting temperature suitable for 60 high outdoor temperatures (e.g. summer days) may lead to poor performances for lower 61 external temperatures (e.g. winter days). Since a case by case analysis will ultimately 62

discriminate between the possible combinations of parameters, the availability of physical 63 models that permits to discriminate a priori between the different possible alternatives 64 is highly desirable. Accordingly, the goal of the present study is to propose such a nu-65 merical model and to illustrate for generic situations how it can be used to analyze the 66 overall thermal effectiveness of a PCM-composite board and compare it with that of a 67 plain board of the same thickness. This contribution is organized as follows: first, the 68 proposed model and the method of solution are presented and validated. Then, the model 69 is applied to the academic configuration of a harmonic external temperature modulation 70 around the melting temperature chosen equal to the indoor temperature. The sensitivity 71 to the nature of the insulating matrix is investigated by considering a more conductive 72 material (i.e. cement). The case of a non-smooth harmonic modulation of the outdoor 73 temperature is also investigated to evidence the effect of small-scale perturbations. Fi-74 nally, the results obtained for a more realistic but still idealized external temperature 75 evolution representative of either a summer or winter generic day are discussed. 76

## 77 2. Numerical Modelling

#### 78 2.1. Physical model and assumptions



Figure 1: Sketch of the modelled system: the composite board and a volume of control containing PCM spheres undergoing phase change.

The unsteady thermal behavior of an insulation board containing microscopic spherical inclusions of a PCM is investigated. The diameter of the monodisperse PCM particles is  $d = 100 \ \mu m$  [21]. The PCM spheres are homogeneously dispersed in a solid matrix (see Fig. 1). The wall has a relatively small thickness compared to its lateral dimensions

which allows us to use a one-dimensional model for the heat transfer through it. The heat 83 transfer model considers thermal conduction in the matrix and thermal conduction inside 84 the PCM inclusions along with melting and crystallization phenomena combined with an 85 appropriate boundary condition at the interface. As the inclusions are small in diameter 86  $(100 \ \mu m)$ , the natural convection inside these PCM inclusions is not taken into account 87 when they are in liquid state (i.e. the Rayleigh number is well below 1). In the equation 88 of heat governing the thermal transfer in the wall, appears a source term  $\Phi_i$  corresponding 89 to the power exchanged between the solid matrix and the PCM spheres, namely: 90

$$\int_{V_i} (1-\phi)(\rho c_p) \frac{\partial T}{\partial t} dV = \int_{S_i} k_{\text{eff}} \vec{\nabla} T \cdot \vec{d} S + \Phi_i$$
(1)

<sup>91</sup> where  $V_i$  is a control volume within the matrix surrounded by a surface  $S_i$ .  $\phi$  is the volume <sup>92</sup> fraction of PCM contained in a control volume  $V_i$ . The source term  $\Phi_i$  representing the <sup>93</sup> heat flux exchanged between the spheres and the matrix of volume  $(1 - \phi)V_i$  is detailed <sup>94</sup> below. The effective thermal conductivity of the composite  $k_{\text{eff}}$  that appears in Eq. (1) <sup>95</sup> was estimated using the Maxwell's model [22]:

$$k_{\rm eff} = k_m \frac{k_d + 2k_m + 2\phi(k_d - k_m)}{k_d + 2k_m - \phi(k_d - k_m)}.$$
(2)

<sup>96</sup> where  $k_d$  is the thermal conductivity of the dispersed PCM as given by Eq. 5 and  $k_m$ <sup>97</sup> corresponds to average value of the thermal conductivity for the whole matrix.

The finite volume method is used to resolve Eq. (1). Thus, the thickness of the wall is divided into N control volumes of gradual increasing size  $\{V_i, i = 1 \rightarrow N\}$  (from the boundary to the center). The number of inclusions in a control volume is [23]:

$$\Lambda_i = \frac{6\phi V_i}{\pi d^3} \tag{3}$$

where d stands for the diameter of the spheres.

The  $\Lambda_i$  spheres in each control volume are identical and are supposed to follow the same thermal or phase change process, thus, a unique sphere is modeled per control volume, representing the kinetics of the other spheres. The "enthalpy" finite volume method is used to model the heat transfer with phase change within the N different spheres. This method is based on an enthalpy formulation of the heat equation (used here in its temperature form) applied to both liquid and solid phases. Thus, a unique mesh (or grid) cover the two media (liquid and solid). The kinetics of the phase change (freezing or melting) is related to the evolution of the liquid phase fraction f of the PCM. The heat equation inside the spheres reads as:

$$\int_{v_i} (\rho c_p)_d \frac{\partial T}{\partial t} \mathrm{d}v = \int_{s_i} k_d \vec{\nabla} T \cdot \vec{\mathrm{d}}s - \int_{v_i} \rho_d L_m \frac{\partial f}{\partial t} \mathrm{d}v \tag{4}$$

The model is unidimensional, formulated in spherical coordinates. The spheres are divided into M equal control volumes (the radius is unequally divided).  $v_i$  is the control volume delimited by the two spheres of radii  $r_i$  and  $r_{i-1}$ . Only the central volume (i = 0) has a spherical shape. The last term of Eq. (4) accounts for the evolution of the local liquid fraction in the control volume  $v_i$ . The properties  $\Psi$  (density, thermal conductivity and specific heat) of the dispersed PCM are calculated as:

$$\Psi_d = f \Psi_{\rm MCP}^{\rm liquid} + (1 - f) \Psi_{\rm MCP}^{\rm solid}.$$
(5)

The boundary condition for this model is of Dirichlet type at the sphere surface, i.e. 117 the instantaneous temperature of the control volume of the composite board containing 118 the sphere is imposed at the outer surface of this sphere. In the other hand, two types of 119 boundary conditions are applied to the wall. At one side of the composite board (x = 0), 120 a generic unsteady boundary condition is applied. Considering the diversity of possible 121 external conditions (external convection and radiative exchanges), a sinusoidal evolution 122 of the external wall temperature is imposed. This behaviour is representative of what is 123 experimentally observed for example by Ismail and Castro (see Fig. 17 of [13]) and is 124 expressed as: 125

$$T(x=0,t) = \overline{T} - A\sin(2\pi t/\tau) \quad \text{with } \tau = 1 \text{ day.}$$
(6)

At the other side of the board (x = L), a steady convective boundary condition is applied with a heat transfer coefficient  $h = 10 W/m^2$  °C :

$$k_{\text{eff}} \left. \frac{\partial T}{\partial x} \right|_{L} = h[T_{\infty} - T(L, t)] \quad \text{at } x = L.$$
 (7)

This condition is a simplified representation of the behavior of an indoor medium maintained at a fixed temperature  $T_{\infty}$  by an air conditioning system for example (heating and/or cooling).

#### <sup>131</sup> 2.2. Numerical algorithms

In the scope of the present study, the supercooling phenomenon is neglected and the 132 PCM is considered as a pure material melting at a fixed temperature  $T_m$ . This assumption 133 can be justified by the fact that low degrees of supercooling are obtained for slow cooling 134 rates [24] as it is the case for daily periodically changing temperatures. Furthermore, the 135 addition of nucleating agent in the PCM can reduce the degree of supercooling which is 136 crucial for the heat storage application. Thus, the phase change front is modeled as a thin 137 interface (1 grid cell having 0 < f < 1). The modeling of the progression of this front 138 coupled to the update of the liquid fraction field f is achieved using the "new source" 139 algorithm of Voller [25]. The field of f is updated iteratively within each time step [26], 140 in this way, the updated value of  $f_i^{k+1}$  at iteration k+1 and control volume i is calculated 141 as follows: 142

$$f_i^{k+1} = f_i^k + \frac{dt \ a_i^k}{\rho L_m v_i} (T_i - T_m),$$
(8)

where  $a_i^k$  is the coefficient of  $T_i$  in the discretized version of Eq. (4). This update is followed by an overshoot/undershoot correction:

$$f_i^{k+1} = \begin{cases} 0 & \text{if } f_i^{k+1} < 0\\ 1 & \text{if } f_i^{k+1} > 1. \end{cases}$$
(9)

To easily ensure that the temperature at the phase change front is equal to the melting 145 temperature  $T_m$ , the energy equation is penalized at the computational cells belonging to 146 the phase change front  $(0 < f_i < 1)$ . This procedure is performed by adding a penalization 147 source term, equal to  $10^9 \times T_m$ , to the RHS term of energy equations corresponding to 148 these cells. This practice accelerates the convergence of the f updating algorithm, and 149 the number of iterations needed to reach convergence  $(|f_i^{k+1} - f_i^k| < \varepsilon_f)$  may be lowered 150 to 2 or even 1 depending on the size of the mesh and the time-step value. The value of 151 the tolerance  $\varepsilon_f$  was fixed to  $10^{-4}$ . 152

The spatial discretization of Eqs.(1) and (4) relies on centered difference schemes with second order accuracy, while the time scheme is implicit and first order. The Thomas algorithm is used to resolve the resulting tridiagonal linear system. The time step size dt has to be sufficiently small  $dt \leq 10^{-3} s$  to ensure a strong coupling between the two models (matrix and spheres models). For the different configurations (different board thicknesses L, different PCM fractions  $\phi$ ), sufficiently fine grids were used to ensure the <sup>159</sup> grid independence of the results. These values were chosen after the mesh size and time <sup>160</sup> step dependency studies presented in the next section. Thus, a wall of thickness L = 5cm<sup>161</sup> was typically divided into N = 80 control volumes, while M = 20 was used for the spheres. <sup>162</sup> Initially, the whole composite material was considered at a uniform temperature slightly <sup>163</sup> higher than  $T_m$ , thus the whole PCM was at the liquid state f = 1.

The coupling algorithm between the different models (the board and sphere models) proceeds as follows:

166 **Step 1:** At each time step, the N phase change models (sphere models, Eq. 4) are 167 advanced in time for a duration of dt.

<sup>168</sup> Step 2: The heat flux at the spheres surface is calculated as:

$$\varphi_i = k_d \left. \frac{\partial T}{\partial r} \right|_{r=d/2} \tag{10}$$

169 Step 3:  $\Phi_i$ , the source term of Eq. (1), is then calculated as:

$$\Phi_i = \Lambda_i \varphi_i(\pi d^2). \tag{11}$$

**Step 4:** Eq. (1) is then resolved for the same time step and the new temperatures of the N control volumes are obtained. These temperatures will be used as the new boundary conditions for the next time step (**Step 1**).

<sup>173</sup> This loop cycle is repeated until convergence is reached.

### 174 2.3. Consistency test, mesh size dependency study and model validation

The model described above takes into account intrinsically both latent and sensible 175 heat of the PCM. To check its consistency, the following test calculation was carried out: 176 a wall containing  $\phi = 20$  % of spherical inclusions, having the same properties as those 177 of the matrix, is considered and its thermal behavior is compared to that of a solid wall 178  $(\phi = 0)$ . Both simulations should yield exactly the same results. The thickness of the 179 wall is L = 50 mm, its properties are those listed in Table 2 and the indoor conditions 180 are the same as in section 3.1. When the temperature of the left boundary varied over 181 time according to Eq. (6), but without crossing the melting temperature of the PCM, 182 (which was modified for this purpose to avoid phase change:  $T_m = 0$  °C for example), a 183



Figure 2: Test of the model implementation: temperature evolutions at the inner boundary (x = L) of a solid wall with and without inclusions. The inclusions have the same properties as the matrix and do not undergo change phase. The temperature of the outer surface (x = 0) is also shown (Eq. 6).  $\tau$  corresponds to one day.

perfect match between the results from the two configurations is observed (see Fig. 2).
As expected, the spheres behave as parts of a homogeneous material.

The choice of the adequate mesh size for the two models (board and sphere), repre-186 senting the best compromise between accuracy and computation cost, has been done after 187 three series of computations, where the N, M and dt parameters have been progressively 188 varied. An example of results provided by such a procedure is given in Fig. 3, for the case 189 of the parameter N (the number of computational cells within the board thickness) and 190 for a board thickness of L = 2.5 cm. N was varied from 20 to 60. Qualitatively speaking, 191 the global behavior proves to be the same for all the mesh sizes. Quantitatively, the results 192 on the coarser grids converge rapidly to the values obtained by the finest one (N = 60), 193 while the relative difference between the values obtained for N = 60 and N = 40 is always 194 below 5 %. Thus, the value N = 40 was selected. Fig. 4 shows the results of a time step 195 dependency study. A reasonable choice corresponds to  $dt = 10^{-3}s$  since for a larger value 196 of  $dt = 10^{-2}s$  parasite oscillations began to appear. A similar analysis (not detailed here) 197 allowed us to choose M = 20. 198

The two parts of the implemented model were validated separately since no reference solution is available (to the authors knowledge) for a system of mono-dispersed PCM



Figure 3: Results obtained for different mesh sizes N of the composite board model with L = 25 mm and  $\phi = 20$  % (M = 20).

spheres in a matrix. Thus, the unsteady model of heat conduction through a board 201 was compared successfully to the classical 1D analytical solution, while the sphere phase 202 change model was validated against reference solutions given in the literature. Yang and 203 Zhao [27] proposed a solution to the spherical Stefan problem during solidification. A 204 finite difference approach combined with explicit and implicit Euler time integration was 205 developed to solve the Stefan problem involving liquid-solid moving interfaces. The non-206 linearities introduced by the moving boundary were simplified by the use of a convenient 207 transformation of dimensionless variables. 208

They compared their results to those obtained using the iterative analytical series solution of Davis and Hill [28], which is an approximate analytical solution. As an example, it is possible to compare in Tab.1 the present results with those of Refs. [27] and [28]. The selected quantity represents the number of days  $t/\tau$  necessary to reach a complete solidification. It has been obtained for a mesh of M = 20 and for different values of the Stefan number (*Ste*). The agreement is quite good.

#### 215 3. Results

### <sup>216</sup> 3.1. Effect of board thickness and PCM amount

The composite considered in this study consists of a solid matrix formed by a thermally insulating material containing a dispersed paraffin PCM. The properties of the matrix material and of the PCM are given in Table 2. Monodisperse spherical PCM are considered

![](_page_11_Figure_0.jpeg)

Figure 4: Internal heat flux obtained with different time step values dt for a board of L = 25 mm and  $\phi = 20$  % (N = 40; M = 20).

with a diameter  $d = 100 \ \mu m$ . The selected values of L are 10, 15, 20, 25, 30 and 50 mm and the considered values of the fraction of PCM  $\phi$  range from 0 to 50 %. Simulations represent a total observation time of five days  $(5\tau)$ .

In this section, the mean external temperature T of Eq. (6) is taken equal to the 223 melting temperature  $\overline{T} = T_m = 20$  °C and the amplitude fixed to A = 10 °C (i.e. T(0,t)224 oscillating between 10 and 30 °C). This simplified signal is chosen so as to limit the 225 number of parameters of the study (no difference between the mean temperature and the 226 melting temperature. Usually, the meting point of the phase change material is chosen 227 in order to match with the average temperature of the climate zone considered). In this 228 section also, the indoor temperature  $T_{\infty}$  (Eq. 7) was taken equal to  $T_m$  as well, for the 229 sake of simplicity i.e. to avoid the introduction of an additional parameter  $(T_m - T_\infty)$  in 230 the analysis. These simplifications help to focus on the role of  $\phi$  and L. The importance 231 of the gap between the different temperatures is addressed in section 3.4. 232

The propagation of the heat flux within the wall is hampered by both the thermal resistance of the matrix and by the solid-liquid phase change of the PCM. The temperature of the inner face of the wall T(x = L) is obtained by the computation and is used to deduce the heat flux crossing this surface as:

$$\varphi(x = L) = h(T_{\infty} - T(x = L)) \tag{12}$$

In Fig. 5, the evolution of this quantity for four different board thicknesses L and five

Ste	Our Results	Yang and Zhao [27]	Davis and Hill [28]
Number	(M = 20)		
0.01	16.8356	16.8231	16.8327
0.02	8.4932	8.4863	8.4987
0.1	1.809	1.8068	1.8272
0.2	0.9669	0.9654	0.9887
1	0.2750	0.2747	0.2970
2	0.1797	0.1797	0.1988
10	0.0871	0.0881	0.0997

Table 1: Dimensionless time to complete solidification: our results compared to those of Refs. [27] and [28].

Table 2: Properties of the studied materials

Property	$k \; [Wm^{-1}K^{-1}]$	$\rho \; [kg \; m^{-3}]$	$c_p \; [J \; kg^{-1}K^{-1}]$	$L_m \left[J \ kg^{-1}\right]$
Insulating matrix	0.03	900	1200	_
Liquid PCM	0.15	780	2200	$2.3~{\times}10^5$
Solid PCM	0.20	780	2000	_
Cement	1	2000	900	_

PCM percentages  $\phi$  is given and compared with the case without PCM ( $\phi = 0$ , PCM 238 free material). It is observed that for the thin board case L = 10 mm, and even for high 239 values of  $\phi$ , the effect of the phase change, which stops the propagation of heat towards 240 the inside, is effective for only a short period of time, after which the flux increases 241 rapidly and reaches values higher than that of the flux of the PCM free case. In fact, 242 at the end of the phase change, the one-phase PCM (solid or liquid) has a much higher 243 thermal conductivity than that of the matrix (see Tab.2), the effective conductivity of 244 the composite being the more important as  $\phi$  is higher. For thicker walls (L = 15 and 245 20 mm), the time interval during which the phase change occurs is longer, delaying the 246 moment at which the wall becomes purely conductive and that occurs after the reversal 247 of the external temperature signal, which limits the negative impact of the higher PCM 248 conductivity. 249

Beyond  $L \ge 25$  mm and for some values of  $\phi$  ( $\ge 20\%$ ), the phase change process remains incomplete during a whole cycle and along the wall thickness. As a consequence, no heat flux crosses the wall during the whole process. The presence within the wall of a

![](_page_13_Figure_0.jpeg)

Figure 5: Heat flux crossing walls of thickness equal to 10, 15, 20 and 25 mm and with different PCM percentages  $\phi$ .

![](_page_14_Figure_0.jpeg)

Figure 6: Cumulative total energy (Eq. 13) crossing the indoor surface of the wall in both directions for different thicknesses and different PCM percentages.

phase change front (i.e. a zone where the PCM spheres are in a two-phase state) acts as
a thermal barrier.

In order to give a comparison of the behavior of a large number of possible  $(L, \phi)$ combinations, a unique average quantity  $E_t$  is defined. It represents the daily total energy that crosses a unit area of the inner wall surface in both directions (averaged over a 5-day period):

$$E_t = \frac{1}{5} \int_0^{5\tau} |\varphi(x=L)| dt = \frac{1}{5} \int_0^{5\tau} |h(T_\infty - T(x=L))| dt$$
(13)

Thus,  $E_t$  is the theoretical energy needed to counterbalance (by heating or cooling) the effect of heat fluxes crossing the wall. This quantity is given in Fig. 6 for a wide range of L and  $\phi$  values. By analyzing in this figure the behavior of the L = 10 mm board, it can be seen that the addition of PCM to the matrix, even at a low percentage, has a negative effect on its thermal insulation behavior, since its performances for  $\phi > 0$  are lower than those obtained for the PCM free case ( $\phi = 0$ ).

For L = 15 mm, the addition of a percentage of PCM such as  $\phi \leq 30\%$  has a positive effect that increases as  $\phi$  is increased, up to a value of  $\phi \simeq 30\%$ . Beyond this value the insulation performances of the wall decrease, yet remaining better than those of a PCM free board. Thus, for this thickness, the addition of such a high percentage of PCM  $(\phi > 30\%)$  is not justified, at least for cost reasons, since better performances can be

![](_page_15_Figure_0.jpeg)

Figure 7: Total liquid fraction of the dispersed PCM for 3 wall thicknesses L = 15, 20 and 25 mm.

achieved by slightly increasing the thickness (see L = 20 mm and  $\phi = 0$ ). The board of thickness L = 20 mm exhibits performances that improve continuously with the increase of the amount of PCM, but without reaching the limit of  $E_t = 0$  (permanent thermal barrier). This limit is almost reached by the board of L = 25 mm from  $\phi \ge 20\%$ .

Actually, as seen from the curves of Fig. 7, which give the total liquid fraction of PCM 274 of all the inclusions of the composite board, for L = 20 mm, complete solidification and 275 fusion occur for all  $\phi$  values at every cycle. On the other hand, for L = 25 mm and from 276  $\phi > 20\%$ , the phase change of the PCM is not complete at every cycle, which indicates 277 the permanent presence of a two-phase zone at  $T = T_m$  that sweeps through the wall 278 thickness between x = 0 and L without disappearing. Therefore, it is very interesting to 279 choose the conditions that keep as long as possible the PCM in a two-phase state. Of 280 course, this is only possible for situations with very regular cyclic thermal loads. 281

For values of L < 20 mm (see Fig. 6), performance improvement necessarily involves an increase of the thickness L. In contrast, from L = 20 mm, better performances (in comparison to a pure insulation) can be achieved with only 10 % of PCM compared to that obtained when using a 25 mm-thick PCM free board. With a PCM percentage of 40 %, the performances of a board of L = 50 mm of pure insulating material (i.e. PCM free) are recovered. So, in these conditions, if space-saving constraints arise, a pure insulating material can be advantageously replaced by a thinner insulating material containing a dispersed PCM.

#### 290 3.2. Dispersion in a cement-based wall

The system studied in the previous section consists of the dispersion of PCM in a less 291 conducting material (insulating material). Thus, the presence of the PCM has a positive 292 effect as long as the phase change is in progress, since at the end of the phase change, the 293 conductivity of the composite material becomes higher than that of the matrix material. 294 Hence, it is interesting to compare this behavior to the one of a more frequently used 295 system that consists of the dispersion of the PCM within a higher thermal conducting 296 building material such as a mortar or a cement wall [29]. For this purpose, numerical 297 experimentations were conducted concerning such a wall by replacing the thermophysi-298 cal properties of the insulating matrix by those of a typical cement material exhibiting 299 higher thermal conductivity (see Tab. 2). Fig. 8 gives the evolution of the heat flux at 300 internal wall surface and of the global liquid fraction for two wall thicknesses and different 301 percentages of PCM. 302

The addition of PCM to this cement wall has a positive effect on the reduction of the 303 heat flux crossing the wall whatever the percentage and the wall thickness. Obviously, 304 the more PCM is added the more pronounced is this effect. Since the PCM conductivity 305 is below that of the cement, there is no inversion of the effect after the end of the phase 306 change process, as it is the case for the insulation matrix (see Fig. 5). However, contrarily 307 to an insulating material, the dispersion of PCM in a cement wall implies that aspects of 308 material strength should be examined, because these types of material are usually used 309 in the structure. The non inversion of the effect of PCM inclusion, can also be obtained 310 for other building materials such as gypsum boards since their thermal conductivity is 311 comparable to that of PCM. 312

![](_page_17_Figure_0.jpeg)

Figure 8: Heat flux (top) crossing a cement wall and total liquid fraction (bottom) of the dispersed PCM for wall thicknesses of 20 and 50 mm with different PCM percentages  $\phi$ .

## 313 3.3. Effect of small scale stochastic fluctuations of the external temperature

The results presented above were obtained for a smooth sinusoidal variation of the 314 external temperature boundary condition. In the following, the sensitivity of these results 315 to the presence of small fluctuations of the external temperature signal is examined. 316 These fluctuations are supposed to mimick the indirect effects that external conditions 317 modifications (clouds passage or/and wind speed and direction fluctuations for example) 318 could exert on the external wall temperature. To that end, the temperature signal T(t) is 319 expressed as the sum of three terms  $T(t) = \overline{T} + T'_p(t) + T'_s(t)$ , with  $\overline{T}$  being the temporal 320 mean value,  $T'_p$  the periodic (sinusoidal) variation and  $T'_s$  a stochastic fluctuation. The 321 last one is obtained by resolving a stochastic differential equation of the Langevin's type 322 [30], that writes as: 323

$$dT'_{s}(t) = \frac{-T'_{s}(t)dt}{\Lambda_{T}} + \sigma_{T'_{s}}\sqrt{\frac{2}{\Lambda_{T}}}dW_{t}$$
(14)

where  $W_t$  represents a Wiener's process. The initial condition  $T'_s(0)$  is chosen as a Gaussian random variable having a zero mean value and a variance  $\sigma^2_{T'_s}$ . The numerical solution of

![](_page_18_Figure_0.jpeg)

Figure 9: The external temperature signal with superimposed small scale stochastic fluctuations (a), time evolution of the corresponding temperature at the inner surface x = L for a board of thickness L = 15 mm and for  $\phi = 30$  % (b) and the evolution of the total liquid fraction (c). The case of an insulating matrix is considered here.

these equation is obtained using the "hybrid" method [31] given as:

$$T'_{s}(t + \Delta t) = exp\left(-\frac{\Delta t}{\Lambda_{T}}\right)T'_{s}(t) + \sigma_{T'_{s}}\sqrt{1 - exp\left(-\frac{2\Delta t}{\Lambda_{T}}\right)\omega(t)}$$
(15)

where  $\omega(t)$  denotes an independent random normal variable of zero mean value and variance unity i.e.  $\omega(t) \in N(0, 1)$ . Following Wilson and Zhuang [32], the choice of  $\Delta t = \frac{\Lambda_T}{10}$ leads to a discrepancy error less than 2 % when compared to the theoretical Gaussian probability density function of  $T'_s$ .

Fig. 9 displays the signal obtained by the above-mentioned method for the parameters  $\Lambda_T = 1800 \ s$  (an integral time scale representative for instance of that of the passage of clouds) and  $\sigma_{T'_s} = 0.9$  (representing the rms amplitude of the fluctuations) and gives the temperature evolution at the inner surface of the wall obtained when the signal is applied as an external boundary condition. It is clear that for the conditions considered, the sensitivity of the thermal behavior of the board to the presence of small-scale fluctuations in the outside temperature is relatively weak, and its impact on both temporal variation of inner wall temperature (x = L) and total liquid fraction  $F_l$  is marginal.

Thus, subject to confirmation of the relevance of the generated fluctuations, these results indicate that using a purely harmonic outside temperature signal is sufficient to account for the dynamics of the thermal behavior of the wall.

### 343 3.4. Effect of seasonal weather (winter/summer)

Using a composite board as an insulation implies that this material is integrated to 344 a wall or a building envelope on a yearly basis, and as a consequence, its integration 345 should lead to an overall positive budget over the passing seasons. Thus, the choice of the 346 melting temperature of the PCM has a crucial importance. In this study, the question put 347 forward is the following: "For which conditions is it interesting to replace a pure insulation 348 board (i.e. PCM free) by a PCM-composite one having the same thickness?". So, the 349 question is not about the relevance of superimposing an additional PCM-composite board 350 to a wall. Furthermore, the question of the cost of materials is not addressed, only the 351 energetic point of view is dealt with. 352

In the present study, the thermal behavior of a PCM-free material and that of a composite one are compared during two typical days representing summer and winter seasons, respectively. The corresponding external temperature variations were taken as:

356

Summer: 
$$T(x = 0, t) = 27 - 7\sin(2\pi t/\tau)$$
 [°C] (16)

Winter: 
$$T(x = 0, t) = 5 - 7\sin(2\pi t/\tau)$$
 [°C] (17)

Thus, the same amplitude is taken for the two signals  $(7 \ ^{\circ}C)$  while the mean tem-357 peratures are 27 °C and 5 °C for summer and winter days, respectively. The indoor 358 temperatures was chosen to be 26 °C and 20 °C which are close to the standard settings 359 for HVAC systems for summer and winter seasons. We note that contrarily to the pre-360 vious sections, the mean temperatures are here different from the indoor temperatures, 361 particularly for the winter day. The gap with the melting temperature is analyzed here 362 by studying the behavior of PCMs having different  $T_m$  temperatures. This analysis was 363 done for a unique board (L = 25 mm and  $\phi = 20 \%$ ) whose characteristics were chosen 364

![](_page_20_Figure_0.jpeg)

Figure 10: Heat flux crossing the internal surface of a board ( $L = 25 \text{ mm}, \phi = 20 \%$ ) with PCMs of different  $T_m$  and during typical summer and winter days.

using the results of Fig. 6. Thus, the selected board has the minimal L and  $\phi$  values that yield an almost null crossing energy  $E_t$ .

The results presented in Fig. 10 give the time evolution of the heat flux crossing the 367 indoor side of the board for the two typical days considered. For the summer day, the 368 melting temperatures are ranging from 20 to 30  $^{\circ}C$  and the results are compared to the 369 case of a PCM free material ( $\phi = 0$  %). The whole crossing energies per day  $E_t$  (Eq. 13) 370 are summarised in Fig. 11(a). In these figures, it can be noticed that the case of  $T_m = 26$ 371 °C (equal to the indoor target temperature) gives the best results, while the case  $T_m = 27$ 372 °C (equal to the mean external temperature) behaves worse but remains better than all 373 other  $T_m$  values, whose results are even worse than those obtained with the PCM free 374 board ( $\phi = 0$  %, Fig. 11(a)). In Fig. 12(a), that gives the total liquid fraction of the 375 PCM, it is observed that for  $T_m = 26$  °C and 27 °C comparable amounts of PCM were 376 solidified/melted respectively (but larger compared to the other PCMs). It is clear that 377 the best choice for  $T_m$  is to be as close as possible to the indoor temperature to maintain 378 most of the time in the board a uniform temperature zone ( $\simeq T_m$ ), located between the 379 melting front and the internal surface, that will be limiting the heat flux. 380

For the winter day, none of the  $T_m$  choices ranging from 5 to 26 °C perform better than the PCM free counterpart. All the global results are comparable (Fig. 11(b)) for all the PCMs, with a slight advantage though for lower melting temperatures. Thus, even if the phase change process takes place within the board (Fig. 12(b)), the temperature gradient is sufficiently high to generate a more important heat flux related to the higher
 conductivity of the PCM-composite.

Even if it is clearly not relevant for a winter weather, the value  $T_m = 26$  °C has been 387 retained to have a global overview of the annual behavior of the insulating wall. It appears 388 that the addition of PCM to an insulating matrix permits to save  $2.9 \times 10^5 J/m^2$  per 389 summer day, while it causes a loss of  $5.34 \times 10^5 \ J/m^2$  per winter day. Thus, in order to 390 have an annual positive budget, compared to a PCM free insulation, this board should 391 be used in hot climatic zones featuring more summer-like days than winter ones. Results 392 with similar trends have been reported by Izquierdo-Barrientos et al. [18] and Ye et al. 393 [33]. 394

![](_page_21_Figure_2.jpeg)

Figure 11: Cumulative total energy  $E_t$  (Eq. 13) crossing the indoor surface of the board in both directions for typical summer and winter days and for different  $T_m$  ( $L = 25 \text{ mm}, \phi = 20 \%$ ). The values over the bars are the ratios  $E_t/E_t(\phi = 0\%)$  that give a comparison to the PCM free case.

## <sup>395</sup> 4. Conclusion

In this study, the thermal behavior of a composite material consisting of a micro-396 dispersed PCM in an insulating polymer matrix is analyzed. The targeted application 397 is the thermal insulation and a gain of thermal inertia of a building envelope. By using 398 two coupled finite volume models, the behavior of the composite board was studied when 399 submitted to a cyclic harmonic thermal excitation. Different board thicknesses (L) were 400 considered as well as various volume percentages of PCM inclusions ( $\phi$ ). It has been 401 observed that for a thin board, the introduction of PCM has a negative effect on its 402 behavior, as it increases its overall thermal conductivity. It was also shown that with 403

![](_page_22_Figure_0.jpeg)

Figure 12: Total liquid fraction of PCM inside a board ( $L = 25 \text{ mm}, \phi = 20 \%$ ) with PCMs of different melting temperatures  $T_m$  and during typical summer and winter days.

some combinations of L and  $\phi$ , it is possible to durably maintain an active phase change 404 front within the board which then behaves as a genuine thermal barrier. To date, this 405 feature is not commonly reported. Indeed, it is usually considered that the effectiveness of 406 the system may be considerably reduced if the PCM is not able to completely solidify or 407 melt. The results also revealed how pure insulating boards could be favorably replaced by 408 thinner boards enriched with micro-dispersed PCM allowing the reduction of the overall 409 thickness of the insulation. It was also shown that the temperature variations within the 410 material are weakly sensitive to the presence of small scale fluctuations of the external 411 temperature, representing transient climatic variations. We confirmed also that replacing 412 a pure insulation (i.e. PCM free) by a PCM-composite insulation should be studied with 413 care on a yearly basis, since a well behaving material in summer may be a very poor 414 choice during winter. Thus, the PCM-composite board should be optimized (thickness, 415 % of PCM, melting temperature, thermal properties of the matrix) taking into account 416 the climate in which the building is located and the internal and external heat loads. 417

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508 Nomenclature

A	Temperature amplitude $(K)$
$c_p$	Specific heat $(J \ kg^{-1}K^{-1})$
d	PCM inclusions diameter $(m)$
dt	Integration time step $(s)$
$\int f$	Local liquid fraction of PCM
h	Heat transfer coefficient $(W.m^{-2}.K^{-1})$
k	Thermal conductivity $(W.m^{-1}.K^{-1})$
L	Board thickness $(m)$
$L_m$	PCM latent heat of melting $(J.kg^{-1})$
N	Number of control volumes (Matrix discretization)
M	Number of control volumes (PCM inclusion discretization)
r	Radial coordinate in a PCM inclusion $(m)$
S	V control volume boundary
Ste	Stefan number $= c_p \Delta T / L_m$
8	v control volume boundary
t	Time (s)
T	Temperature $(K)$
$\overline{T}$	Time averaged temperature $(K)$
T'	Temperature fluctuation $(K)$
v	Control volume (PCM inclusion discretization)
V	Control volume (Matrix discretization)
$W_t$	Wiener process
x	Spatial coordinate normal to the board $(m)$
Greek symbols	
$\epsilon_{f}$	Convergence parameter
$\Lambda_i$	Number of PCM inclusions in $V_i$
$\Lambda_T$	Integral time scale $(s)$

arphi	Heat flux $(W.m^{-2})$	
$\phi$	PCM volumic fraction	
$\Phi$	Source term	
ρ	Density $(kg.m^{-3})$	
σ	Standard deviation of the stochastic signal	
au	One-day period	
Subscripts		
d	Relative to the dispersed PCM	
eff	Effective	
i	Control volume index	
m	Melting	
p	Periodic	
8	Stochastic	
$\infty$	Relative to indoor conditions	
Superscripts		
k	Iteration index	
Acronym		
PCM	Phase change material	